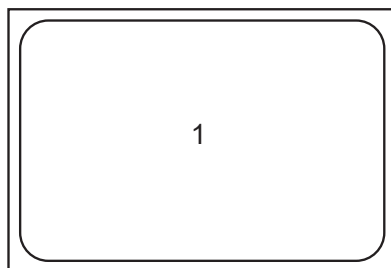


## Product Overview

3300V, 90A, Silicon Carbide (SiC) Schottky Diode bare die.



CATHODE  
(BACKSIDE CONNECTION)



ANODE  
(PAD 1)

### Features

- No reverse recovery
- Low forward voltage
- Low leakage current
- RoHS compliant

### Benefits

- High switching frequency
- Low switching losses
- Low noise (EMI) switching
- Higher reliability systems
- Increased system power density

### Applications

- Power Factor Correction (PFC)
- Anti-parallel diode
  - Switch-mode power supply
  - Inverters/converters
  - Motor controllers
- Freewheeling diode
  - Switch-mode power supply
  - Inverters/converters
- Snubber/clamp diode

# 1. Device Specifications

This section shows the specifications of this device.

## 1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of this device.

**Table 1-1.** Absolute Maximum Ratings

Symbol	Parameter		Ratings	Unit
V <sub>R</sub>	Maximum DC reverse voltage		3300	V
V <sub>RRM</sub>	Maximum peak repetitive reverse voltage			
V <sub>RWM</sub>	Maximum working peak reverse voltage			
I <sub>F</sub>	Maximum DC forward current <sup>1</sup>	T <sub>C</sub> = 25 °C	187	A
		T <sub>C</sub> = 135 °C	92	
		T <sub>C</sub> = 145 °C	78	
I <sub>FRM</sub>	Repetitive peak forward surge current (tp = 8.3 ms, half sine wave) <sup>1</sup>		258	
I <sub>FSM</sub>	Non-repetitive forward surge current (tp = 8.3 ms, half sine wave) <sup>1</sup>		615	
P <sub>TOT</sub>	Total power dissipation <sup>1</sup>	T <sub>C</sub> = 25 °C	1500	W
		T <sub>C</sub> = 135 °C	400	
		T <sub>C</sub> = 145 °C	300	

**Note:**

1.  $I_F$  values for  $< 0.10\text{ °C/W}$  die to heatsink thermal resistance based on TO-247 package. Current capability may be bond wire limited.

## 1.2 Thermal and Mechanical Characteristics

The following table shows the thermal and mechanical characteristics of this device.

**Table 1-2.** Thermal and Mechanical Characteristics

Symbol	Characteristic/Test Conditions	Min.	Typ.	Max.	Unit
$T_J, T_{STG}$	Operating junction and storage temperature range	-55	—	175	°C
$T_{proc}$	Assembly soldering temperature (10 minutes maximum)	—	—	375	

Recommended storage: The die should be stored (as shipped) in dry nitrogen with an ambient temperature of 25 °C.

ESD practices should comply with JESD-625.

## 1.3 Electrical Performance

The following table shows the static characteristics of this device.  $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

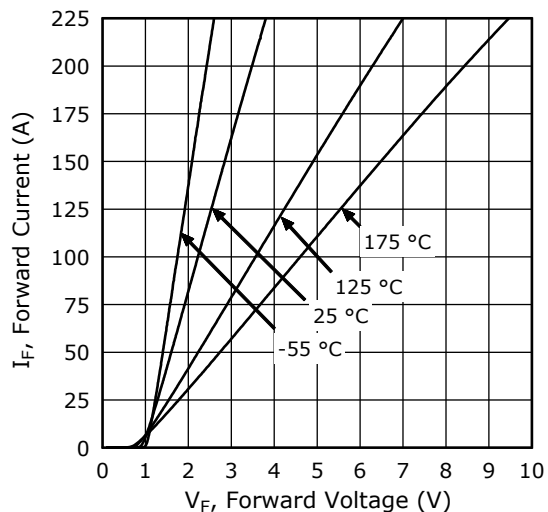
**Table 1-3.** Static Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$V_F$	Forward voltage <sup>1</sup>	$I_F = 90\text{A}$ , $T_J = 25\text{ }^{\circ}\text{C}$	—	2.1	2.5	V
		$I_F = 90\text{A}$ , $T_J = 175\text{ }^{\circ}\text{C}$	—	4.3	—	
$I_{RM}$	Reverse leakage current <sup>1</sup>	$V_R = 3300\text{V}$ , $T_J = 25\text{ }^{\circ}\text{C}$	—	15	90	$\mu\text{A}$
		$V_R = 3300\text{V}$ , $T_J = 175\text{ }^{\circ}\text{C}$	—	150	—	
$Q_C$	Total capacitive charge <sup>1</sup>	$V_R = 1650\text{V}$	—	927	—	nC
$C_J$	Junction capacitance <sup>1</sup>	$V_R = 1\text{V}$ , $f = 1\text{ MHz}$	—	6326	—	pF
		$V_R = 1100\text{V}$ , $f = 1\text{ MHz}$	—	361	—	
		$V_R = 2200\text{V}$ , $f = 1\text{ MHz}$	—	256	—	

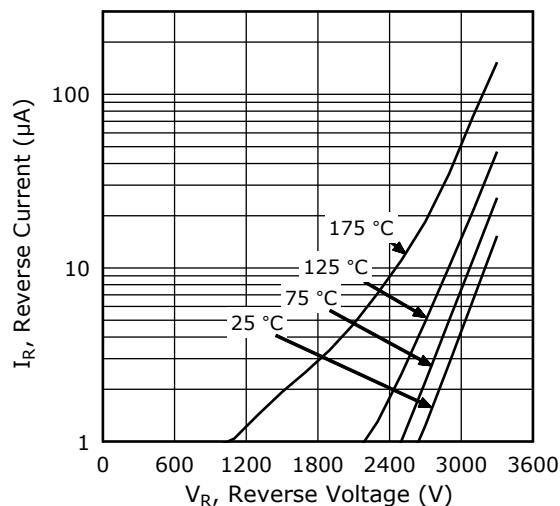
## 2. Typical Performance Curves

This section shows the typical performance curves of this device.

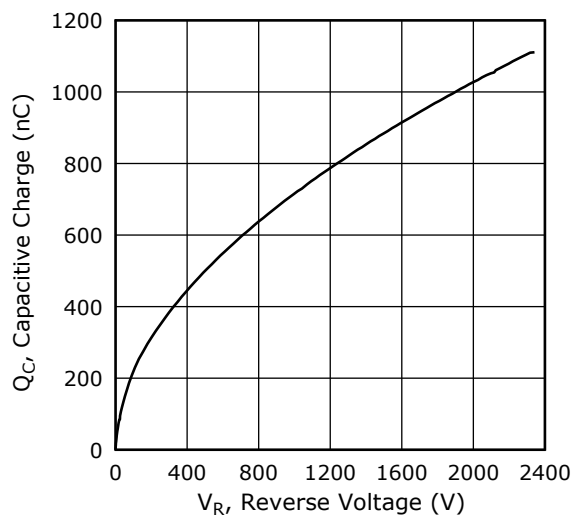
**Figure 2-1. Forward Current vs. Forward Voltage**



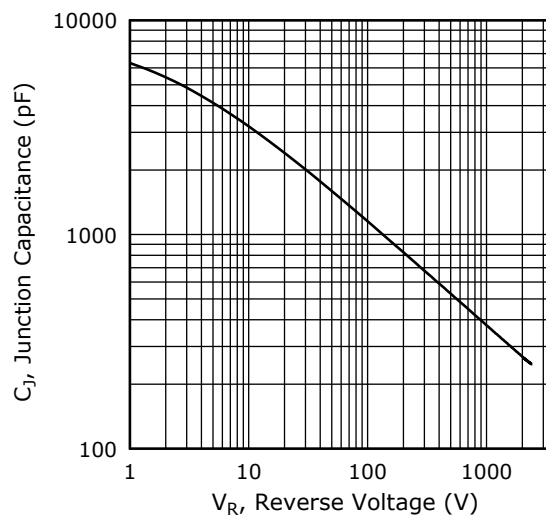
**Figure 2-2. Reverse Current vs. Reverse Voltage**



**Figure 2-3. Total Charge vs. Reverse Voltage**



**Figure 2-4. Capacitance vs. Reverse Voltage**



### 3. Die Specification

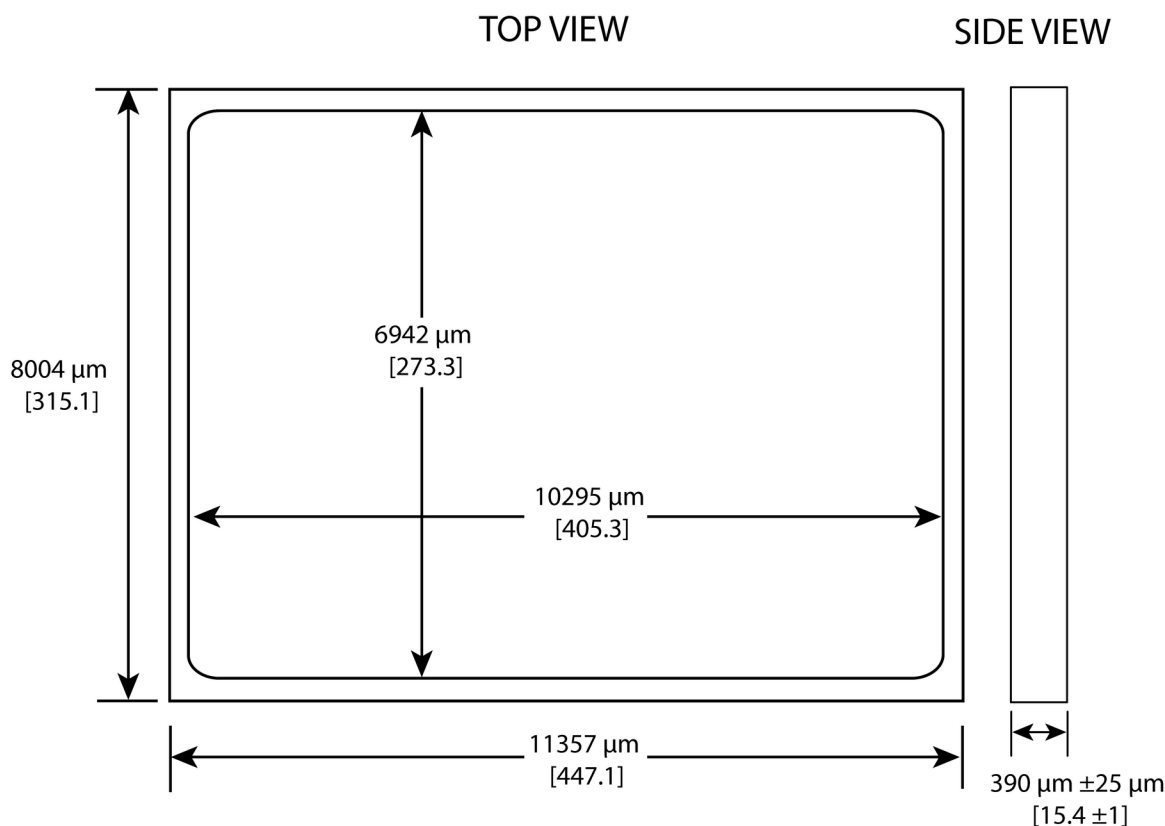
This section shows the die specification of this device.

#### 3.1 Die Layout

The dimensions in this drawing are the nominal dimensions including the scribe street. The final die dimensions are determined by the scribe frame at each fabrication location and the dicing process at each assembly location.

The dimensions in the figure below are in  $\mu\text{m}$  and [mils].

**Figure 3-1.** Die Outline Drawing



#### Die Layout

Description	Thickness	Component
Top metal - Anode	5.0 $\mu\text{m}$	Al/Cu
Backside metal - Cathode	1.0 $\mu\text{m}$	Ag

## 4. Revision History

Table 4-1. Revision History

Revision	Date	Description
B	07/2024	The following changes are made in this revision of the document: <ul style="list-style-type: none"><li>• Updated <a href="#">Product Overview</a>.</li><li>• Updated <a href="#">Table 1-1</a> and <a href="#">Table 1-3</a>.</li><li>• Updated <a href="#">2. Typical Performance Curves</a>.</li></ul>
A	03/2022	Document created.

## Microchip Information

### The Microchip Website

Microchip provides online support via our website at [www.microchip.com/](http://www.microchip.com/). This website is used to make files and information easily available to customers. Some of the content available includes:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip design partner program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

### Product Change Notification Service

Microchip's product change notification service helps keep customers current on Microchip products. Subscribers will receive email notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, go to [www.microchip.com/pcn](http://www.microchip.com/pcn) and follow the registration instructions.

### Customer Support

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Embedded Solutions Engineer (ESE)
- Technical Support

Customers should contact their distributor, representative or ESE for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in this document.

Technical support is available through the website at: [www.microchip.com/support](http://www.microchip.com/support)

### Microchip Devices Code Protection Feature

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not mean that we are guaranteeing the product is "unbreakable". Code protection is constantly evolving. Microchip is committed to continuously improving the code protection features of our products.

### Legal Notice

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure

that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at [www.microchip.com/en-us/support/design-help/client-support-services](http://www.microchip.com/en-us/support/design-help/client-support-services).

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

## Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, TimeCesium, TimeHub, TimePictra, TimeProvider, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, EyeOpen, GridTime, IdealBridge, IGaT, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, MarginLink, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mSiC, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICKit, PICtail, Power MOS IV, Power MOS 7, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQL, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, Turing, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.



All other trademarks mentioned herein are property of their respective companies.

© 2024, Microchip Technology Incorporated and its subsidiaries. All Rights Reserved.

ISBN: 978-1-6683-0040-4

## Quality Management System

For information regarding Microchip's Quality Management Systems, please visit [www.microchip.com/quality](http://www.microchip.com/quality).

# Worldwide Sales and Service

AMERICAS	ASIA/PACIFIC	ASIA/PACIFIC	EUROPE
<b>Corporate Office</b> 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: <a href="http://www.microchip.com/support">www.microchip.com/support</a> Web Address: <a href="http://www.microchip.com">www.microchip.com</a>	<b>Australia - Sydney</b> Tel: 61-2-9868-6733 <b>China - Beijing</b> Tel: 86-10-8569-7000 <b>China - Chengdu</b> Tel: 86-28-8665-5511 <b>China - Chongqing</b> Tel: 86-23-8980-9588 <b>China - Dongguan</b> Tel: 86-769-8702-9880 <b>China - Guangzhou</b> Tel: 86-20-8755-8029 <b>China - Hangzhou</b> Tel: 86-571-8792-8115 <b>China - Hong Kong SAR</b> Tel: 852-2943-5100 <b>China - Nanjing</b> Tel: 86-25-8473-2460 <b>China - Qingdao</b> Tel: 86-532-8502-7355 <b>China - Shanghai</b> Tel: 86-21-3326-8000 <b>China - Shenyang</b> Tel: 86-24-2334-2829 <b>China - Shenzhen</b> Tel: 86-755-8864-2200 <b>China - Suzhou</b> Tel: 86-186-6233-1526 <b>China - Wuhan</b> Tel: 86-27-5980-5300 <b>China - Xian</b> Tel: 86-29-8833-7252 <b>China - Xiamen</b> Tel: 86-592-2388138 <b>China - Zhuhai</b> Tel: 86-756-3210040	<b>India - Bangalore</b> Tel: 91-80-3090-4444 <b>India - New Delhi</b> Tel: 91-11-4160-8631 <b>India - Pune</b> Tel: 91-20-4121-0141 <b>Japan - Osaka</b> Tel: 81-6-6152-7160 <b>Japan - Tokyo</b> Tel: 81-3-6880-3770 <b>Korea - Daegu</b> Tel: 82-53-744-4301 <b>Korea - Seoul</b> Tel: 82-2-554-7200 <b>Malaysia - Kuala Lumpur</b> Tel: 60-3-7651-7906 <b>Malaysia - Penang</b> Tel: 60-4-227-8870 <b>Philippines - Manila</b> Tel: 63-2-634-9065 <b>Singapore</b> Tel: 65-6334-8870 <b>Taiwan - Hsin Chu</b> Tel: 886-3-577-8366 <b>Taiwan - Kaohsiung</b> Tel: 886-7-213-7830 <b>Taiwan - Taipei</b> Tel: 886-2-2508-8600 <b>Thailand - Bangkok</b> Tel: 66-2-694-1351 <b>Vietnam - Ho Chi Minh</b> Tel: 84-28-5448-2100	<b>Austria - Wels</b> Tel: 43-7242-2244-39 Fax: 43-7242-2244-393 <b>Denmark - Copenhagen</b> Tel: 45-4485-5910 Fax: 45-4485-2829 <b>Finland - Espoo</b> Tel: 358-9-4520-820 <b>France - Paris</b> Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79 <b>Germany - Garching</b> Tel: 49-8931-9700 <b>Germany - Haan</b> Tel: 49-2129-3766400 <b>Germany - Heilbronn</b> Tel: 49-7131-72400 <b>Germany - Karlsruhe</b> Tel: 49-721-625370 <b>Germany - Munich</b> Tel: 49-89-627-144-0 Fax: 49-89-627-144-44 <b>Germany - Rosenheim</b> Tel: 49-8031-354-560 <b>Israel - Hod Hasharon</b> Tel: 972-9-775-5100 <b>Italy - Milan</b> Tel: 39-0331-742611 Fax: 39-0331-466781 <b>Italy - Padova</b> Tel: 39-049-7625286 <b>Netherlands - Drunen</b> Tel: 31-416-690399 Fax: 31-416-690340 <b>Norway - Trondheim</b> Tel: 47-72884388 <b>Poland - Warsaw</b> Tel: 48-22-3325737 <b>Romania - Bucharest</b> Tel: 40-21-407-87-50 <b>Spain - Madrid</b> Tel: 34-91-708-08-90 Fax: 34-91-708-08-91 <b>Sweden - Gothenberg</b> Tel: 46-31-704-60-40 <b>Sweden - Stockholm</b> Tel: 46-8-5090-4654 <b>UK - Wokingham</b> Tel: 44-118-921-5800 Fax: 44-118-921-5820